

GENERAL PURPOSE DUAL OPERATIONAL AMPLIFIER

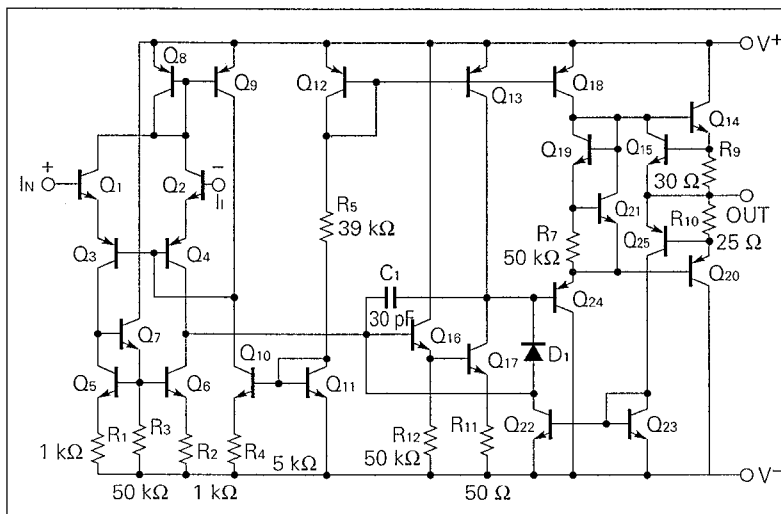
DESCRIPTION

The μPC1458 is a dual general purpose operational amplifier having internal frequency compensating circuits. It is intended for a wide range of analog applications. High common mode voltage range and no latch up tendencies make this amplifier ideal for use as a voltage follower.

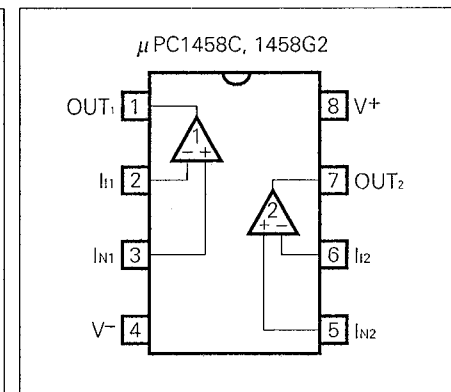
FEATURES

- Internally frequency compensated
- Short circuit protection

EQUIVALENT CIRCUIT (1/2 Circuit)



CONNECTION DIAGRAM (Top View)



ORDERING INFORMATION

PART NUMBER	PACKAGE	QUALITY GRADE
μPC1458C	8 PIN PLASTIC DIP (300 mil)	Standard
μPC1458G2	8 PIN PLASTIC SOP (225 mil)	Standard

Please refer to "Quality grade on NEC Semiconductor Devices" (Document number IEI-1209) published by NEC Corporation to know the specification of quality grade on the devices and its recommended applications.

ABSOLUTE MAXIMUM RATINGS (T_a = 25 °C)

PARAMETER		SYMBOL	μPC1458	UNIT
Voltage between V ⁺ and V ⁻ (Note 1)		V ⁺ - V ⁻	-0.3 to +36	V
Differential Input Voltage		V _{ID}	±30	V
Input Voltage (Note 2)		V _I	V ⁻ -0.3 to V ⁺ +0.3	V
Output Voltage (Note 3)		V _O	V ⁻ -0.3 to V ⁺ +0.3	V
Power Dissipation	C Package (Note 4)	P _T	350	mW
	G2 Package (Note 5)		440	mW
Output Short Circuit Duration (Note 6)			Indefinite	sec
Operating Temperature Range		T _{opt}	-20 to +80	°C
Storage Temperature Range		T _{stg}	-55 to +125	°C

- Note 1.** Reverse connection of supply voltage can cause destruction.
- Note 2.** The input voltage should be allowed to input without damage or destruction. Even during the transition period of supply voltage, power on/off etc., this specification should be kept. The normal operation will establish when the both inputs are within the Common Mode Input Voltage Range of electrical characteristics.
- Note 3.** This specification is the voltage which should be allowed to supply to the output terminal from external without damage or destruction. Even during the transition period of supply voltage, power on/off etc., this specification should be kept. The output voltage of normal operation will be the Output Voltage Swing of electrical characteristics.
- Note 4.** Thermal derating factor is -5.0 mW/°C when ambient temperature is higher than 55 °C.
- Note 5.** Thermal derating factor is -4.4 mW/°C when ambient temperature is higher than 25 °C.
- Note 6.** Pay careful attention to the total power dissipation not to exceed the absolute maximum ratings, Notes 4 and 5.

RECOMMENDED OPERATING CONDITIONS

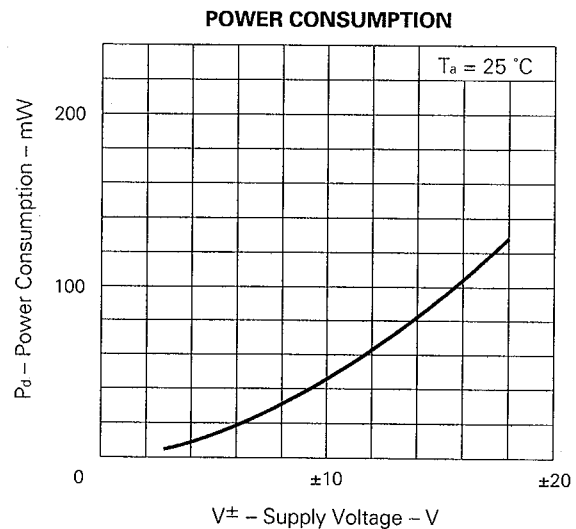
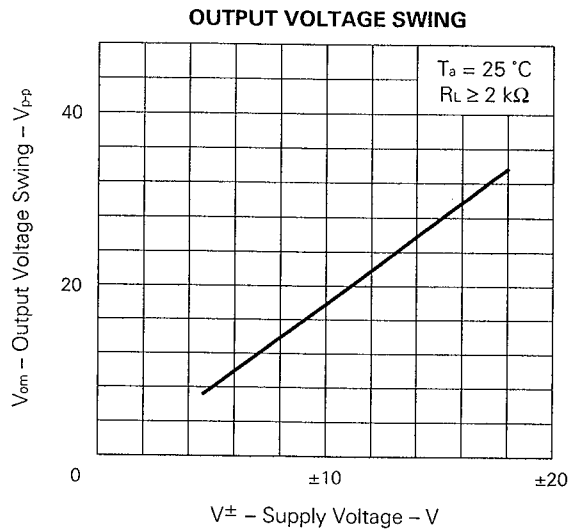
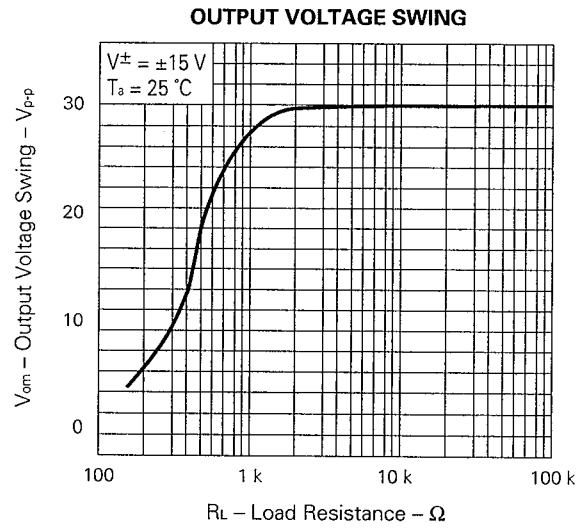
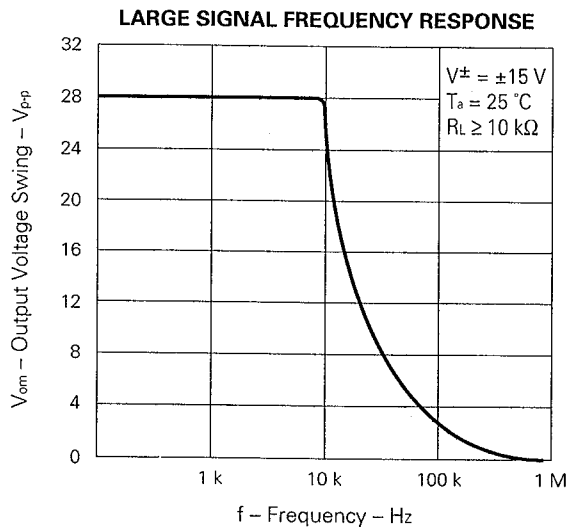
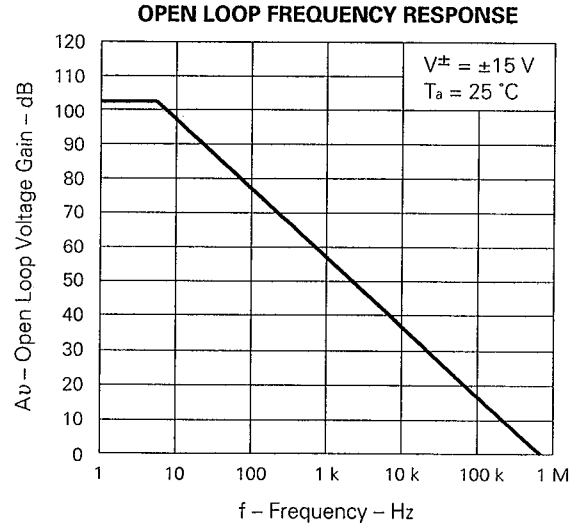
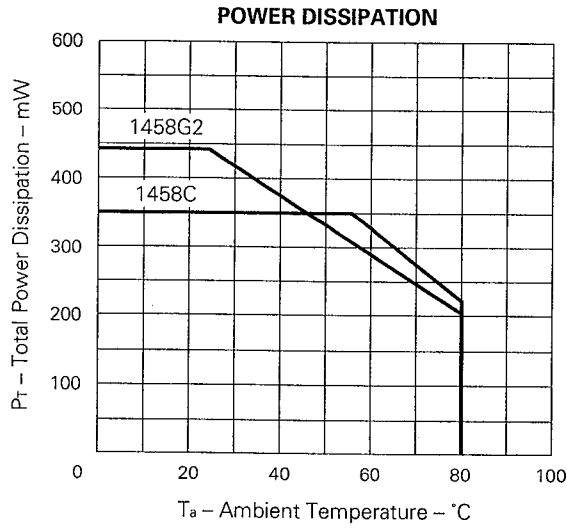
CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply Voltage (Split)	V [±]	±7.5		±16	V
Supply Voltage (V ⁻ = GND)	V ⁺	+15		+32	V
Output Current	I _o		±2	±5	mA

ELECTRICAL CHARACTERISTICS ($V^{\pm} = \pm 15V$, $T_a = 25^{\circ}C$)

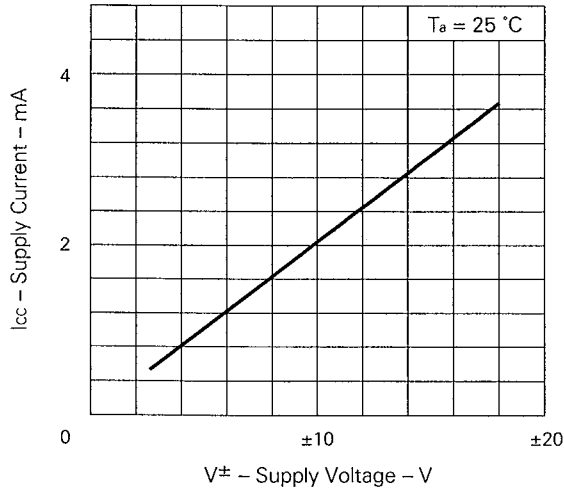
CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS
Input Offset Voltage	V_{io}		± 1.0	± 6.0	mV	$R_s \leq 10\text{ k}\Omega$
Average Input Offset Voltage Drift	$\Delta V_{io}/\Delta T$		± 3		$\mu V/^{\circ}C$	$R_s \leq 10\text{ k}\Omega$
Input Offset Current (Note 7)	I_{io}		± 20	± 200	nA	
Input Bias Current (Note 7)	I_b		80	500	nA	
Input Impedance	R_{in}	0.3	1.0		M Ω	
Large Signal Voltage Gain	A_v	20000	160000			$R_L \geq 2\text{ k}\Omega$, $V_o = \pm 10\text{ V}$
Supply Current	I_{cc}		3.0	5.6	mA	$I_o = 0\text{ A}$, Both Amplifiers
Power Consumption	P_d		90	170	mW	$I_o = 0\text{ A}$, Both Amplifiers
Common Mode Rejection Ratio	CMR	70	90		dB	$R_s \leq 10\text{ k}\Omega$
Supply Voltage Rejection Ratio	SVR		30	150	$\mu V/V$	$R_s \leq 10\text{ k}\Omega$
Output Voltage Swing	V_{om}	± 12	+14 -12		V	$R_L \geq 10\text{ k}\Omega$
Output Voltage Swing	V_{om}	± 10	+13 -11		V	$R_L \geq 2\text{ k}\Omega$
Common Mode Input Voltage Range	V_{icm}		$V^+ - 0.5$ $V^- + 2$		V	
Channel Separation			120		dB	$f = 10\text{ Hz}$, $R_L = 2\text{ k}\Omega$

Note 7. Input bias currents flow into IC. Because each currents are base current of NPN-transistor on input stage.

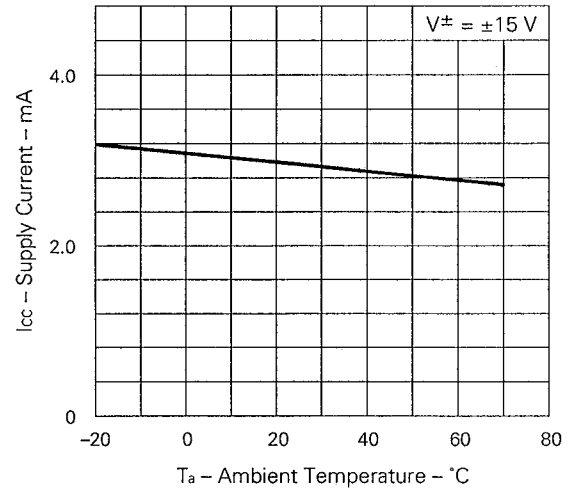
TYPICAL PERFORMANCE CHARACTERISTICS (T_a = 25 °C, TYP.)



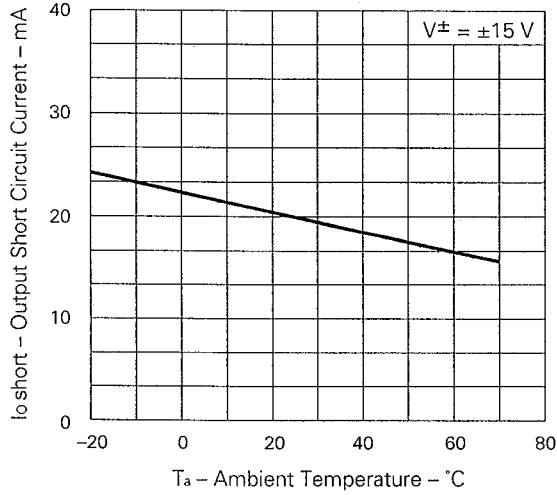
SUPPLY CURRENT



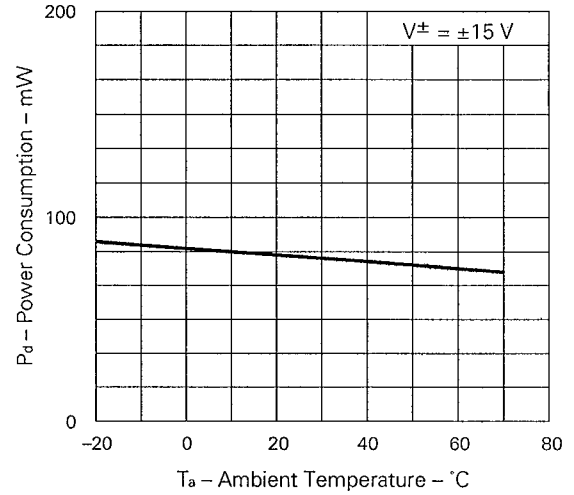
SUPPLY CURRENT



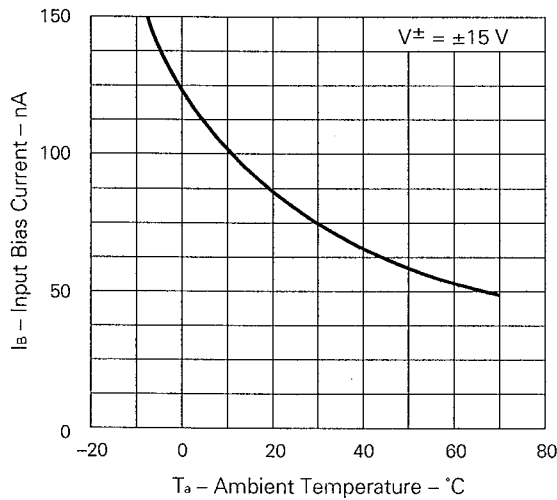
OUTPUT SHORT CIRCUIT CURRENT



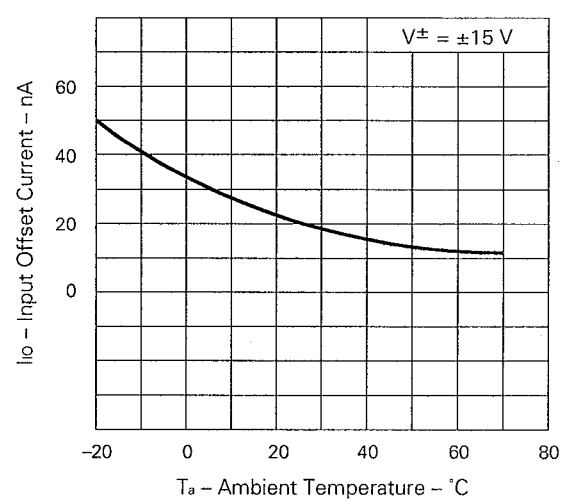
POWER CONSUMPTION



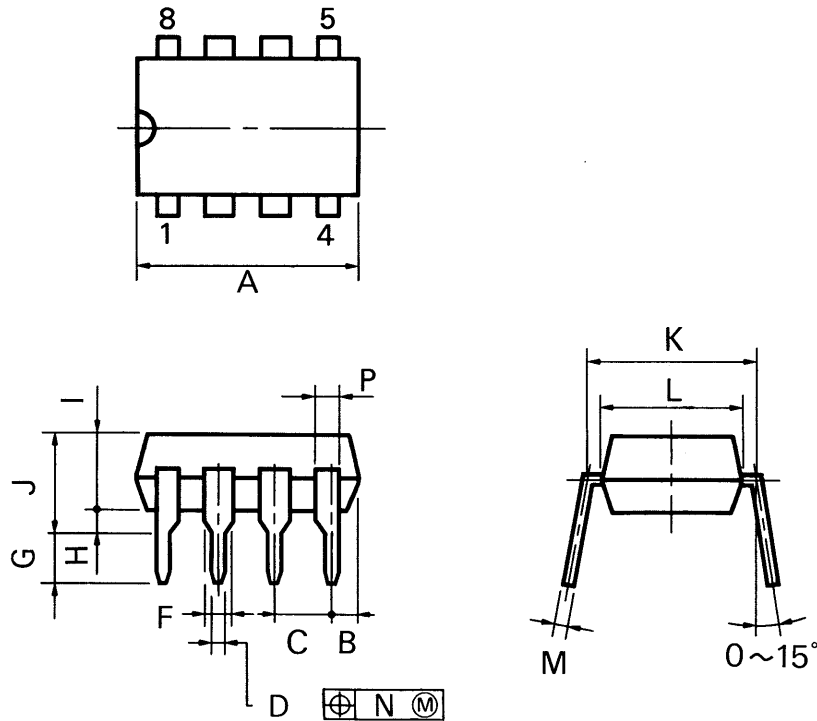
INPUT BIAS CURRENT



INPUT OFFSET CURRENT



8PIN PLASTIC DIP (300 mil)



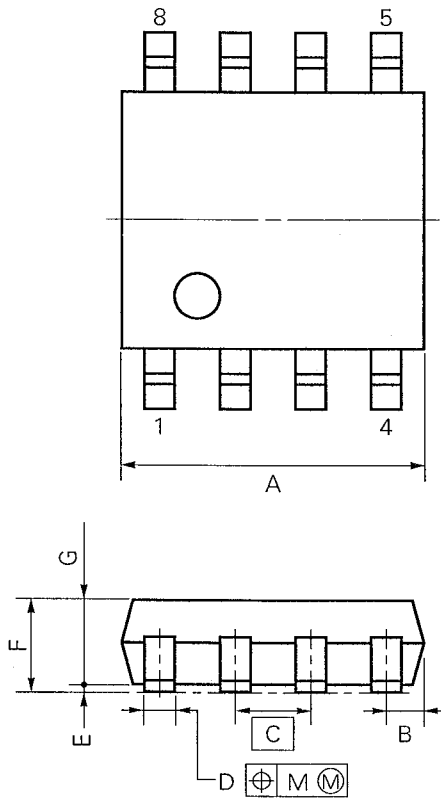
P8C-100-300B,C

NOTES

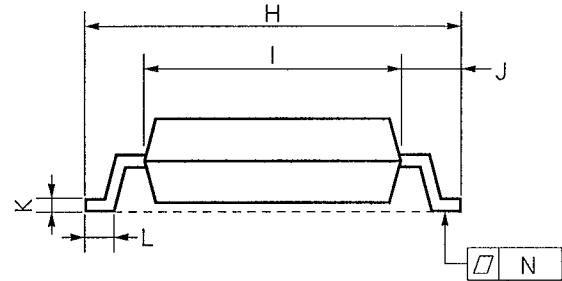
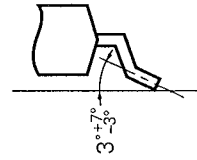
- 1) Each lead centerline is located within 0.25 mm (0.01 inch) of its true position (T.P.) at maximum material condition.
- 2) Item "K" to center of leads when formed parallel.

ITEM	MILLIMETERS	INCHES
A	10.16 MAX.	0.400 MAX.
B	1.27 MAX.	0.050 MAX.
C	2.54 (T.P.)	0.100 (T.P.)
D	0.50 ^{+0.10}	0.020 ^{+0.004} _{-0.005}
F	1.4 MIN.	0.055 MIN.
G	3.2 ^{+0.3}	0.126 ^{+0.012}
H	0.51 MIN.	0.020 MIN.
I	4.31 MAX.	0.170 MAX.
J	5.08 MAX.	0.200 MAX.
K	7.62 (T.P.)	0.300 (T.P.)
L	6.4	0.252
M	0.25 ^{+0.10} _{-0.05}	0.010 ^{+0.004} _{-0.003}
N	0.25	0.01
P	0.9 MIN.	0.035 MIN.

8 PIN PLASTIC SOP (225 mil)



detail of lead end



NOTE

Each lead centerline is located within 0.12 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

S8GM-50-225B-2

ITEM	MILLIMETERS	INCHES
A	5.37 MAX.	0.212 MAX.
B	0.78 MAX.	0.031 MAX.
C	1.27 (T.P.)	0.050 (T.P.)
D	0.40 ^{+0.10} _{-0.05}	0.016 ^{+0.004} _{-0.003}
E	0.1±0.1	0.004±0.004
F	1.8 MAX.	0.071 MAX.
G	1.49	0.059
H	6.5±0.3	0.256±0.012
I	4.4	0.173
J	1.1	0.043
K	0.15 ^{+0.10} _{-0.05}	0.006 ^{+0.004} _{-0.002}
L	0.6±0.2	0.024 ^{+0.008} _{-0.009}
M	0.12	0.005
N	0.15	0.006

RECOMMENDED SOLDERING CONDITIONS

The following conditions (see table below) must be met when soldering this product.

Please consult with our sales offices in case other soldering process is used, or in case soldering is done under different conditions.

TYPES OF SURFACE MOUNT DEVICE

For more details, refer to our document "SEMICONDUCTOR DEVICE MOUNTING TECHNOLOGY MANUAL" (IEI-1207).

[μPC1458G2]

Soldering method	Soldering conditions	Recommended condition symbol
Infrared ray reflow	Peak package's surface temperature: 230 °C or below, Reflow time: 30 seconds or below (210 °C or higher), Number of reflow process: 1, Exposure limit *: None	IR30 - 00 - 1
VPS	Peak package's surface temperature: 215 °C or below, Reflow time: 40 seconds or below (200 °C or higher), Number of reflow process: 1, Exposure limit *: None	VP15 - 00 - 1
Wave soldering	Solder temperature: 260 °C or below, Flow time: 10 seconds or below, Number of flow process: 1, Exposure limit *: None	WS15 - 00 - 1
Partial heating method	Terminal temperature: 300 °C or below, Flow time: 10 seconds or below, Exposure limit *: None	○

* Exposure limit before soldering after dry-pack package is opened.

Storage conditions: 25 °C and relative humidity at 65 % or less.

Note Do not apply more than a single process at once, except for "Partial heating method".

TYPES OF THROUGH HOLE DEVICE

[μPC1458C]

Soldering method	Soldering conditions	Recommended condition symbol
Wave soldering	Solder temperature: 260 °C or below, Flow time: 10 seconds or below	○

[MEMO]

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Application examples recommended by NEC Corporation

Standard: Computer, Office equipment, Communication equipment, Test and Measurement equipment, Machine tools, Industrial robots, Audio and Visual equipment, Other consumer products, etc.

Special: Automotive and Transportation equipment, Traffic control systems, Antidisaster systems, Anticrime systems, etc.